ABSOCIATION CONNECTING ELECTRONICS (NOUSTRIES+) MAterial Composition © Copyright 2005. IPC, Bar international and Pan-Ameri	nockburn, Illinois. A	Il rights reserved untions.	inder both	This docume level parts, t	ent is a declara he declaration	ion of the s encompasse	ubstances es all lowe	within the manufacture r level materials for w	rer listed	item. Note: i nanufacture	if the item is an as r has engineering	sembly with lower responsibility.
	IPC Web Site for Information on IPC-1752 Standard Form http://www.ipc.org/IPC-175x Distribution							ials and N	als and Mfg Information			
Supplier Information												
Company name*	que ID U			Unique ID Authority				Respon	Response Date*			
nsemi									2023-06-08			
tact Name Title - Contact					Phone - Contact*				Email - Contact*			
roduct-Env-Stewards Product Enviro Compliance					NA			Product-Env-Stewards@onsemi.com				
Authorized Representative* Title - Representative				Phone - Representative*				Email - Representative*				
Product-Env-Stewards Product Enviro Complia			mpliance		NA			Produ	Product-Env-Stewards@onsemi.com			
Requester Item Number M	fr Item Number	Mfr Item Name			Effective Date	e Version	N	Manufacturing Site		Weight*	UOM	Unit Type
NO	CP1230D133R2G ANA PWM CU		RRENT-MODE CONT		2023-06-08		1	TH6		71.85	mg	Each
Manufacturing Proccess Information												
Terminal Plating / Grid Array Material	erial Terminal Base Alloy		J-STD-020 MSL	0-020 MSL Rating		Peak Process Body Temperatu		ure Max Time at Peak Temper		ture Numb	ber of Reflow Cy	eles
Matte Tin (Sn) - annealed CU Alloy		1	1		260		С	30	secoi	nds 3		
Comments												
level 1 - maximum time at peak temperature dur	ing soldering is 10-3	0 seconds										
For more information regarding material compo	sition please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	(Pb), Mercury (Hg), Hexavalent Chror	nition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead ury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).								
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted					
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the					
Supplier Digital Signature Ra	stislav Drska	Le								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.33	mg	Supplier	Silicon (Si)	7440-21-3		1.33	mg
Die Attach	2.4	mg	Supplier	Silver (Ag)	7440-22-4		1.8	mg
			Supplier	Epoxy resins	129915-35-1		0.6	mg
Lead Frame :	37.61	mg	Supplier	Silver (Ag)	7440-22-4		0.2257	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0451	mg
			Supplier	Iron (Fe)	7439-89-6		0.8838	mg
			Supplier	Copper (Cu)	7440-50-8		36.4441	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0113	mg
Mold Compound-Black	28.58	mg		Epoxy Phenol Resin	proprietary data		3.0009	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		25.5791	mg
Plating	1.89	mg	Supplier	Tin (Sn)	7440-31-5		1.89	mg
Wire Bond - Cu	0.04	mg	Supplier	Copper (Cu)	7440-50-8		0.04	mg